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PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

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Hideo TANAYA

Application No.: New US Patent Application

Filed: March 9, 2001

Docket No.: 108850

For: PACKAGE SEALING METHOD, MANUFACTURING METHOD OF ELECTRONIC
DEVICE MODULES, SEALING APPARATUS, AND PACKAGE PRODUCTS

PRELIMINARY AMENDMENT

Director of the U.S. Patent and Trademark Office
Washington, D. C. 20231

Sir:

Prior to initial examination, please amend the above-identified application as follows:

IN THE CLAIMS:

Please replace claims 3-4, 7-8, 10-12, and 18-22 as follows:

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3. (Amended) The package sealing method according to claim 1, wherein the case and the lid are fixed to each other by pressure, and thereafter, the bonding member is irradiated with the laser beam.

4. (Amended) The package sealing method according to claim 1, wherein the case is provided with a through hole, and the case and the lid are fixed to each other by vacuum suction using the hole, and thereafter, the bonding member is irradiated with the laser beam.